

ABSTRACT

APPARATUS FOR MOLDING ELECTRONIC COMPONENTS

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A molding apparatus for an electronic device comprises a first mold chase, a second mold chase and a middle plate which is configured to be clamped together with the electronic device between the first mold chase and second mold chase during molding. A molding cavity formed in the middle plate is
10 configured for receiving molding compound. A package pin is mounted on the middle plate to be movable with the middle plate, and a portion of the package pin is positioned to protrude into the molding cavity to form a mark in the molding compound when molding compound is molded around the said portion of the package pin.

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(FIG. 4)